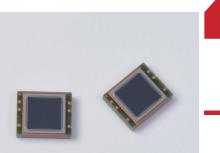


HOTON IS OUR BUSINESS



Two-dimensional PSD

S15534

Surface mount type, high-accuracy position sensitive detector

The S15534 is a surface mount type two-dimensional PSD with excellent position detection characteristics. It is smaller than the conventional S5990-01.

Features

- COB type
- **■** Excellent position detectability
- **■** Small package: 7.21 × 5.96 × 1.5^t mm
- Compatible with lead-free solder reflow

Applications

- Light spot detection
- Pointing device
- Various types of position detection

Options (sold separately)

■ Signal processing circuit for 2-D PSD C4674-01

Structure

Parameter	Symbol	Specification	Unit
Photosensitive area	А	4 × 4	mm
Package	-	Glass epoxy	-
Window material	-	Silicone resin	-

→ Absolute maximum ratings (Ta=25 °C)

Parameter	Symbol	Value	Unit
Reverse voltage	VR max	20	V
Operating temperature*1	Topr	-20 to +60	°C
Storage temperature*1	Tstg	-20 to +80	°C
Soldering temperature	Tsol	260 (3 times)* ²	°C

^{*1:} No dew condensation. When there is a temperature difference between a product and the surrounding area in high humidity environments, dew condensation may occur on the product surface. Dew condensation on the product may cause deterioration in characteristics and reliability.

Note: Exceeding the absolute maximum ratings even momentarily may cause a drop in product quality. Always be sure to use the product within the absolute maximum ratings.

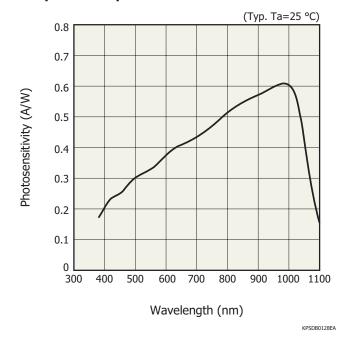
^{*2:} Reflow soldering, JEDEC J-STD-020 MSL 3, see P.5

■ Electrical and optical characteristics (Ta=25 °C)

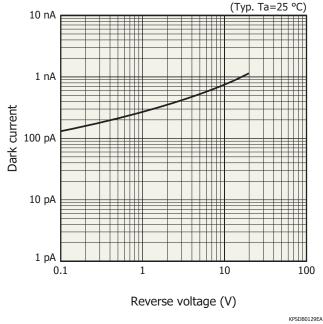
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Spectral response range	λ		-	380 to 1100	-	nm
Peak sensitivity wavelength	λр		-	980	-	nm
Photosensitivity	S	$\lambda = \lambda p$	-	0.6	-	A/W
Interelectrode resistance	Rie	Vb=0.1 V	5	7	15	kΩ
Position detection error	Е	λ =900 nm, VR=5 V light spot: ϕ 0.2 mm* ³	-	±70	±150	μm
Saturation photocurrent	Ist	λ =900 nm, VR=5 V RL=1 k Ω	-	500	-	μΑ
Dark current	ID	VR=5 V	-	0.5	10	nA
Rise time	tr	VR=5 V, RL=1 kΩ λ =900 nm	-	1	-	μs
Terminal capacitance	Ct	VR=5 V, f=10 kHz	-	70	-	pF
Position resolution	ΔR	Io=1 μA, B=1 kHz*3	-	0.7	-	μm

^{*3:} Specified within a circle that is 80% of the photosensitive area. Recommended light spot size: ϕ 0.2 mm or more

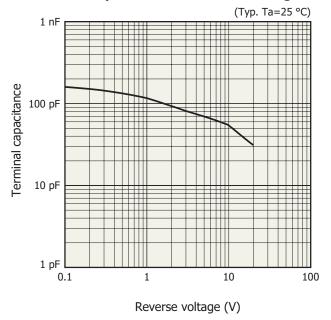
Spectral response



Dark current vs. reverse voltage

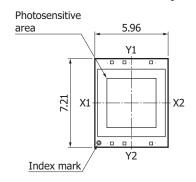


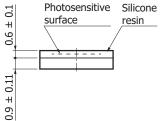
Terminal capacitance vs. reverse voltage

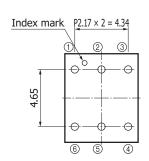


KPSDB0130EA

► Dimensional outline (unit: mm)







Tolerance unless otherwise noted: ± 0.15 Chip position accuracy with respect to package center X, Y \leq ± 0.1

- ① Anode X1 (I1) ② Cathode (common)
- ③ Anode Y1 (I3) ④ Anode X2 (I2)
- ⑤ NC
- ⑥ Anode Y2 (I4)

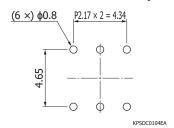
KPSDA0068EA

Conversion formula

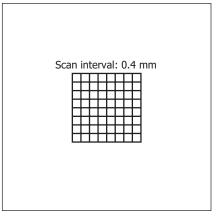
$$\frac{(I2 + I3) - (I1 + I4)}{I1 + I2 + I3 + I4} = \frac{2x}{L}$$
$$\frac{(I2 + I4) - (I1 + I3)}{I1 + I2 + I3 + I4} = \frac{2y}{L}$$

x, y: Position coordinates of light spot: L=4.5 mm

► Recommended land pattern (unit: mm)



Example of position detectability (Ta=25 °C, λ=900 nm, light spot size: φ0.2 mm)



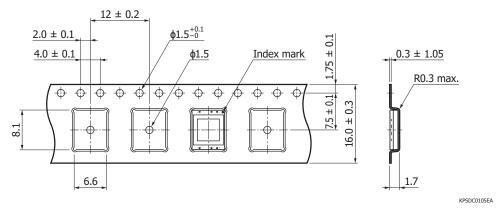
KPSDC0064EA

Standard packing specifications

■ Reel (conforms to JEITA ET-7200)

Outer diameter	Hub diameter	Tape width	Material	Electrostatic characteristics
ф330 mm	ф100 mm	16 mm	PS	Conductive

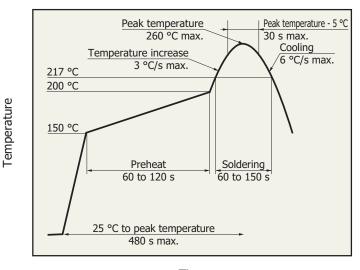
■ Embossed tape (unit: mm, material: PS, conductive)



- Packing quantity500 pcs/reel
- Packing state

 Reel and desiccant in moisture-proof packaging (vacuum-sealed)

Recommended reflow soldering conditions



- · After unpacking, store this device in an environment at a temperature range of 5 to 30 °C and a humidity below 60%, and perform reflow soldering on this device within 168 hours.
- · The effect that the product receives during reflow soldering varies depending on the circuit board and reflow oven that are used. When you set reflow soldering conditions, check that problems do not occur in the product by testing out the conditions in advance.

Time

KSPDB0419EA

Baking

If more than 3 months have passed in the unopened state, or storage conditions are exceeded after opening the package, baking is required to remove moisture before reflow soldering. For the baking, refer to the precautions "Surface mount type products."

■ Recommended baking conditions

Temperature: 120 °C, 3 hours, up to twice

Note: Before setting the baking conditions, perform experiments to confirm that no problems occur with the product.

Related information

https://www.hamamatsu.com/sp/ssd/doc_en.html

- Precautions
- Disclaimer
- · Surface mount type products
- Technical note
- · PSD

Information described in this material is current as of February 2023.

Product specifications are subject to change without prior notice due to improvements or other reasons. This document has been carefully prepared and the information contained is believed to be accurate. In rare cases, however, there may be inaccuracies such as text errors. Before using these products, always contact us for the delivery specification sheet to check the latest specifications.

The product warranty is valid for one year after delivery and is limited to product repair or replacement for defects discovered and reported to us within that one year period. However, even if within the warranty period we accept absolutely no liability for any loss caused by natural disasters or improper product use. Copying or reprinting the contents described in this material in whole or in part is prohibited without our prior permission.

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